

Thyristor Surge Suppressor

Version: A0 2019/5/27

Features

- Excellent capability of absorbing transient surge
- Quick response to surge voltage (nS Level)
- Eliminates overvoltage caused by fast rising transients
- Moisture sensitivity level: level 1
- Non degenerative
- Bi-directional
- Surge rating:4KV@10/700us

Exterior



SMA

Application Information

- Ethernet

Package (top view)



Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

Schematic Symbol



Part Number and Electrical Parameter

Part Number	IDRM@ VDRM		Vs ^① @ Is		VT@ IT		IH	Co ^②
	μA	V	V	mA	V	A	mA	pF
	MAX		MAX		MAX		MIN	MAX
BS4000M	5	400	520	800	4	2.2	15	50

Absolute maximum ratings measured at TA= 25°C RH = 45%-75% (unless otherwise noted).

① Vs is measured at 100KV/S

② Off-state Capacitance is measured at VDC=2V, VRMS=1V, f=1MHz

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Part Numbering System

BS 4000 M
(1) (2) (3)

(1) Bencent Semiconductor Surge Arrester

(2) Product code

(3) Package: SMA

Mark

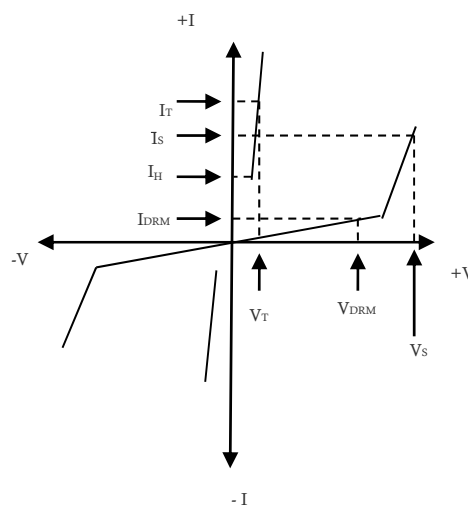


B40NB: Part Number

1904: April, 2019

V-I Curve

Parameters	Definition
V_{DRM}	Peak Off-state Voltage
I_{DRM}	Off-state Current
V_S	Switching Voltage
I_S	Switching Current
I_H	Holding Current
V_T	On-state Voltage
I_T	On-state Current
C_o	Off-state Capacitance



Surge Ratings

Current Waveform	5/320 μ s*
Voltage Waveform	10/700 μ s*
I_{pp}	100A

-Peak pulse current rating (I_{PP}) is repetitive and guaranteed for the life of the product;

-Bencent only makes the test for 5/320 μ s@100A* (10/700 μ s@4KV).

Thermal Considerations

Symbol	Parameter	Value	Unit
T_J	Operating Junction Temperature Range	-40 to +125	$^{\circ}$ C
T_S	Storage Temperature Range	-40 to +150	$^{\circ}$ C

Physical Characteristics

Lead Material	Copper Alloy
Body Material	UL recognized epoxy meeting flammability classification 94V-0
Terminal Finish	100% Matte-Tin Plated

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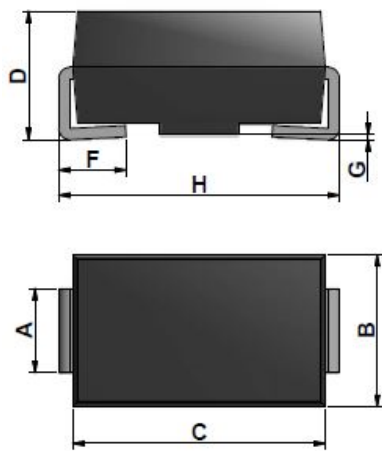
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Environmental Characteristics

Testing Items	Technical Standards
High Temperature Reverse Bias Test	Temperature: $125\pm 3^{\circ}\text{C}$, Bias= $80\%V_{\text{DRM}}$ Time: 168H
High Temperature Life Test	Temperature: 150°C Time: 168H
High-low Temperature Cycle Test	Temperature: From -40°C to 125°C Dwell time: 30min, 100 cycles
High Temperature & High Humidity Test	Temperature: 85°C Humidity: 85% Test time: 168H
Pressure Cooker Test	Temperature: 121°C , 2atm. Humidity: 100% Test time: 24H
Resistance of Soldering Heat	Temperature: $260\pm 5^{\circ}\text{C}$ Time of dip soldering: 10s, 3times

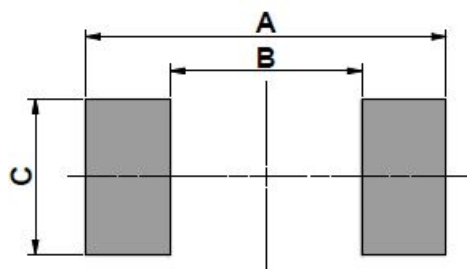
Note: The above testing items can be specified by customers by contacting Bencent service

Product Dimensions



REF.	mm	inch
A	1.5 ± 0.2	0.059 ± 0.008
B	2.7 ± 0.4	0.106 ± 0.016
C	4.4 ± 0.4	0.173 ± 0.016
D	2~2.50	0.079~0.098
F	1.2 ± 0.5	0.047 ± 0.020
G	0~0.5	0~0.020
H	5 ± 0.4	0.197 ± 0.016

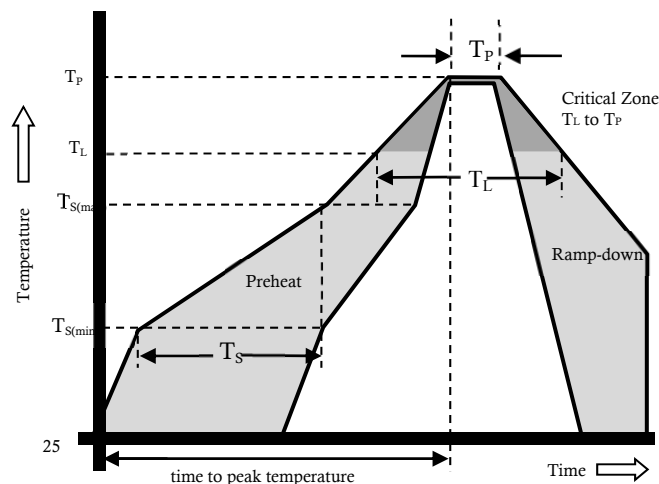
Recommended Soldering Pad



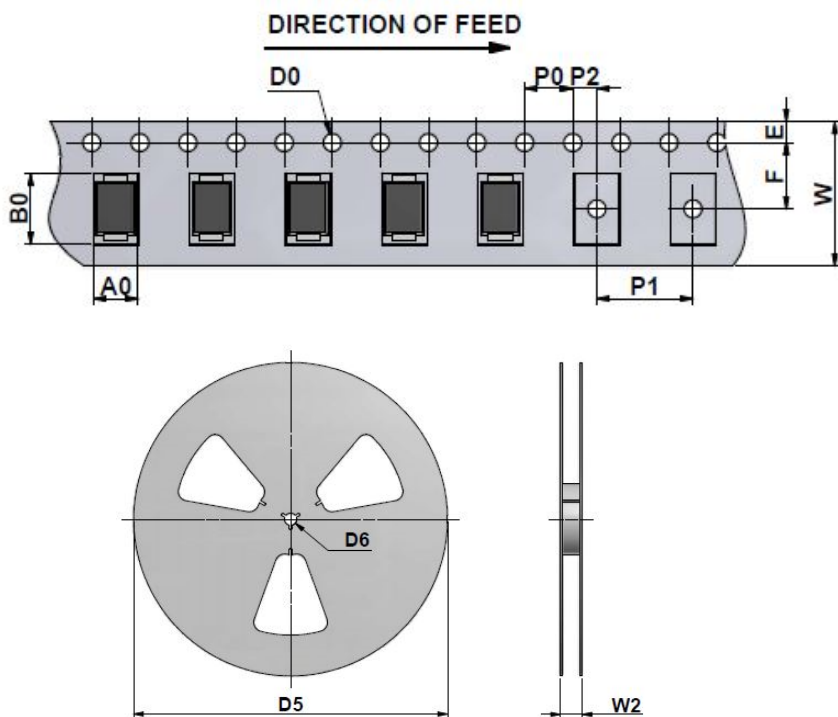
REF	mm	inch
A	6	0.236
B	2	0.079
C	2	0.079

Reflow Profile

Reflow Condition		Pb-Free Assembly
Pre Heat	Temperature Min.	+150°C
	Temperature Max.	+200°C
	Time (Min to Max)	60 – 180 seconds
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (T_L)	60 – 150 seconds
Peak Temp (T_P)		260+0/-5 °C
Time within 5°C of actual Peak Temp (T_P)		8-15 seconds
Ramp-down Rate		6°C/s max
Time 25°C to peak Temp (T_P)		8 min max.
Do not exceed		260°C



Package Reel Information



REF.	mm	inch
W	12±1	0.472±0.039
E	1.75±0.4	0.069±0.016
F	5.5±0.4	0.217±0.016
D0	1.5±0.2	0.059±0.008
P0	4.0±0.3	0.157±0.012
P1	4.0±0.3	0.157±0.012
P2	2.0±0.3	0.079±0.012
A0	2.85±0.4	0.112±0.016
B0	5.4±0.4	0.213±0.016
D5	Ø330	Ø13
D6	Ø13.5±1.0	Ø0.531±0.039
W2	18±2.0	0.709±0.079

Outline	Reel (pcs)	Per Carton (pcs)	Reel Diameters (mm)	Carton Size(mm)		
				L	W	H
Taping	5,000	80,000	330	360	360	385